TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS137

CD74HC86, CD74HCT86

High Speed CMOS Logic
Quad 2-Input EXCLUSIVE OR Gate

August 1997

Features

- **Typical Propagation Delay: 9ns at V_{CC} = 5V, C_L = 15pF, T_A = 25°C**
- **Fanout (Over Temperature Range)**
  - **Standard Outputs . . . . 10 LSTTL Loads**
  - **Bus Driver Outputs . . . . 15 LSTTL Loads**
- **Wide Operating Temperature Range . . . -55°C to 125°C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - **2V to 6V Operation**
  - **High Noise Immunity: N_{IL} = 30%, N_{IH} = 30% of V_{CC} at V_{CC} = 5V**
- **HCT Types**
  - **4.5V to 5.5V Operation**
  - **Direct LSTTL Input Logic Compatibility, V_{IL}= 0.8V (Max), V_{IH} = 2V (Min)**
  - **CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL}, V_{OH}**

Applications

- **Logical Comparators**
- **Parity Generators and Checkers**
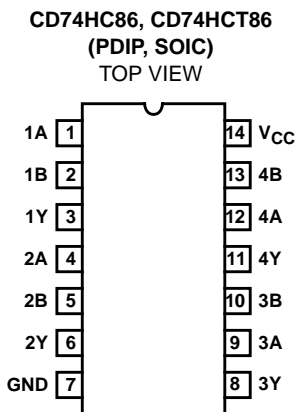- **Adders and Subtractors**

Description

The Harris CD74HC86, CD74HCT86 contain four independent EXCLUSIVE OR gates in one package. They provide the system designer with a means for implementation of the EXCLUSIVE OR function. Logic gates utilize silicon gate CMOS technology to achieve operating speeds similar to LSTTL gates with the low power consumption of standard CMOS integrated circuits. All devices have the ability to drive 10 LSTTL loads. The 74HCT logic family is functionally pin compatible with the standard 74LS logic family.
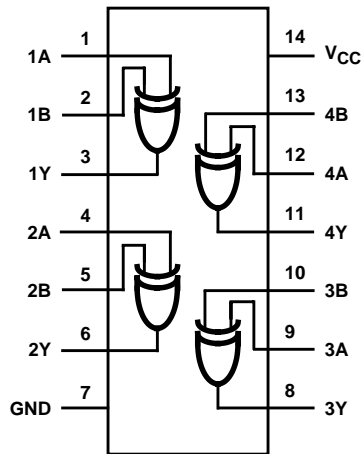
Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC86E	-55 to 125	14 Ld PDIP	E14.3
CD74HCT86E	-55 to 125	14 Ld PDIP	E14.3
CD74HC86M	-55 to 125	14 Ld SOIC	M14.15
CD74HCT86M	-55 to 125	14 Ld SOIC	M14.15
CD54HC86W	-55 to 125	Wafer	
CD54HCT86W	-55 to 125	Wafer	
CD54HC86H	-55 to 125	Die	

NOTE: When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.

Pinout

**CD74HC86, CD74HCT86
(PDIP, SOIC)
TOP VIEW**

```
        ┌───┬──┬───┐
  1A ──┤1      14├── V_CC
  1B ──┤2      13├── 4B
  1Y ──┤3      12├── 4A
  2A ──┤4      11├── 4Y
  2B ──┤5      10├── 3B
  2Y ──┤6       9├── 3A
 GND ──┤7       8├── 3Y
        └──────────┘
```

File Number **1644.1**

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Functional Diagram

```
          1  ┌────────┐ 14
   1A ─────┤          ├──── V_CC
          2 │          │ 13
   1B ─────┤   )D      ├──── 4B
          3 │          │ 12
   1Y ─────┤          ├──── 4A
          4 │          │ 11
   2A ─────┤          ├──── 4Y
          5 │          │ 10
   2B ─────┤   )D      ├──── 3B
          6 │          │ 9
   2Y ─────┤          ├──── 3A
          7 │          │ 8
  GND ─────┤          ├──── 3Y
            └────────┘
```

TRUTH TABLE

INPUTS		OUTPUT
nA	**nB**	**nY**
L	L	L
L	H	H
H	L	H
H	H	L

NOTE: H = High Voltage Level, L = Low Voltage Level

Logic Symbol

nA ──▷○──▷○──┐
             ├─)D──▷○──▷○── nY
nB ──▷○──▷○──┘

CD74HC86, CD74HCT86

Absolute Maximum Ratings

DC Supply Voltage, V_{CC} . . . . -0.5V to 7V
DC Input Diode Current, I_{IK}
  For V_I < -0.5V or V_I > V_{CC} + 0.5V . . . .±20mA
DC Output Diode Current, I_{OK}
  For V_O < -0.5V or V_O > V_{CC} + 0.5V . . . .±20mA
DC Output Source or Sink Current per Output Pin, I_O
  For V_O > -0.5V or V_O < V_{CC} + 0.5V . . . .±25mA
DC V_{CC} or Ground Current, I_{CC} or I_{GND} . . . .±50mA

Operating Conditions

Temperature Range (T_A) . . . . -55°C to 125°C
Supply Voltage Range, V_{CC}
  HC Types . . . . .2V to 6V
  HCT Types . . . . .4.5V to 5.5V
DC Input or Output Voltage, V_I, V_O . . . . 0V to V_{CC}
Input Rise and Fall Time
  2V . . . . 1000ns (Max)
  4.5V. . . . . 500ns (Max)
  6V . . . . 400ns (Max)

Thermal Information

Thermal Resistance (Typical, Note 1) θ_{JA} (^{o}C/W)
  PDIP Package   100
  SOIC Package   180
Maximum Junction Temperature . . . . 150°C
Maximum Storage Temperature Range . . . .-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) . . . . 300°C
  (SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS			25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)	V_{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V_{IH}	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V_{IL}	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} or GND	-	6	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	6	-	-	2	-	20	-	40	µA

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DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS			25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		V_I (V)	I_O (mA)	V_{CC} (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HCT TYPES												
High Level Input Voltage	V_{IH}	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V_{IL}	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V_{OH}	V_{IH} or V_{IL}	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V_{OL}	V_{IH} or V_{IL}	-0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I_I	V_{CC} and GND	0	5.5	-	-	±0.1	-	±1	-	±1	µA
Quiescent Device Current	I_{CC}	V_{CC} or GND	0	5.5	-	-	2	-	20	-	40	µA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note 2)	ΔI_{CC}	V_{CC} -2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	µA

NOTE:

2. For dual-supply systems theorectical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

INPUT	UNIT LOADS
All	1

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications table, e.g. 360µA max at 25°C.

Switching Specifications Input t_r, t_f = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay, Input to Output (Figure 1)	t_{PLH}, t_{PHL}	C_L = 50pF	2	-	-	120	-	150	-	180	ns
			4.5	-	-	24	-	30	-	36	ns
			6	-	-	20	-	26	-	31	ns
Propagation Delay, Data Input to Output Y	t_{PLH}, t_{PHL}	C_L = 15pF	5	-	9	-	-	-	-	-	ns
Transition Times (Figure 1)	t_{TLH}, t_{THL}	C_L = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns

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Switching Specifications Input t_r, t_f = 6ns **(Continued)**

PARAMETER	SYMBOL	TEST CONDITIONS	V_{CC} (V)	25°C MIN	25°C TYP	25°C MAX	-40°C TO 85°C MIN	-40°C TO 85°C MAX	-55°C TO 125°C MIN	-55°C TO 125°C MAX	UNITS
Input Capacitance	C_I	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	-	22	-	-	-	-	-	pF
HCT TYPES											
Propagation Delay, Input to Output (Figure 2)	t_{PLH}, t_{PHL}	C_L = 50pF	4.5	-	-	32	-	40	-	48	ns
Propagation Delay, Data Input to Output Y	t_{PLH}, t_{PHL}	C_L = 15pF	5	-	13	-	-	-	-	-	ns
Transition Times (Figure 2)	t_{TLH}, t_{THL}	C_L = 50pF	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	C_I	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	C_{PD}	-	5	-	27	-	-	-	-	-	pF

NOTES:

3. C_{PD} is used to determine the dynamic power consumption, per gate.

4. $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ where f_i = input frequency, C_L = output load capacitance, V_{CC} = supply voltage.
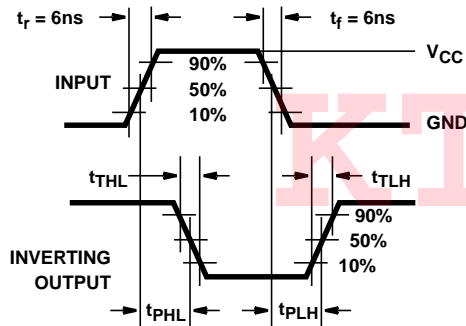
Test Circuits and Waveforms

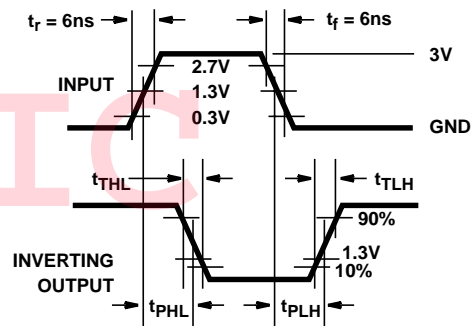**FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

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